



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:) Group Art Unit: 2827
Michael John Watson)
Serial Number 09/954,528)
Filed: September 17, 2001)
Title: IMPROVED ADHESIVES FOR)
SEMICONDUCTOR APPLICA-)
TIONS EFFICIENT PROCESSES)
FOR PRODUCING SUCH)
DEVICES AND THE DEVICE)
PER SE PRODUCED BY THE)
EFFICIENT PROCESSES)
Attorney Docket: DC - 4952) April 28, 2003
AMENDMENTS TO
THE ABSTRACT

Assistant Commissioner
For Patents
Washington DC 20231

Dear Sir:

Please find enclosed a new page setting forth the amended ABSTRACT.

Respectfully submitted,

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ABSTRACT

Die attach adhesives and methods for their use, along with the devices that are obtained by the use of the methods. Using semiconductor chips as an example, the
5 adhesives and the method for using them provides an interface between a chip (die) and the chip support. The method includes creating a space between the chip and the chip support of a given sized opening by using inorganic insulator particles having an average particle size of 1 μm to 1000 μm and a major axis to minor axis ratio of about 1.0 to 1.5.

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